

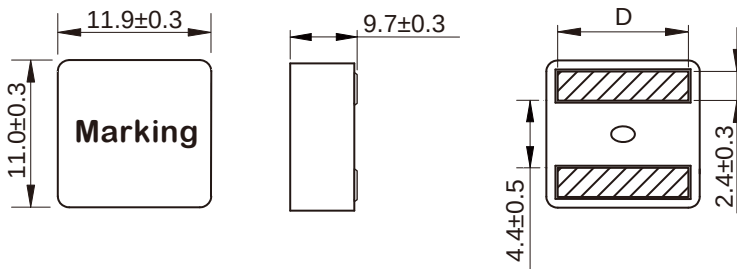
Wire Wound Molded SMD Power Inductors Size 1010



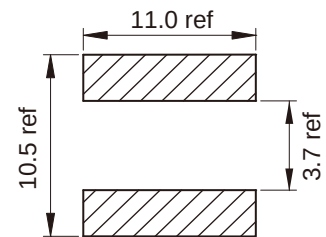
- So saturation
- High current, low DCR, high efficiency
- Very low acoustic noise and very low leakage flux noise
- High reliability
- 100% Lead(Pb)-Free and RoHS compliant
- Operating temperature -55~+125 °C (Including self - temperature rise)
- Quantity: 300pcs

- Note PC power system, incl. IMVP-6
- DC/DC converter

Dimensions: [mm]



Land Pattern: [mm]

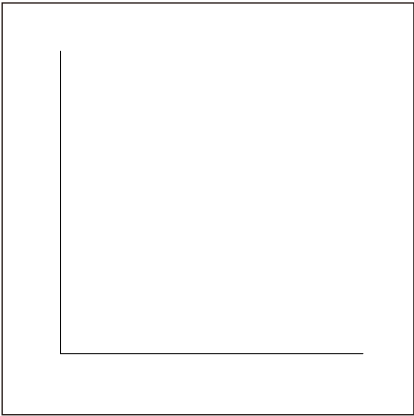
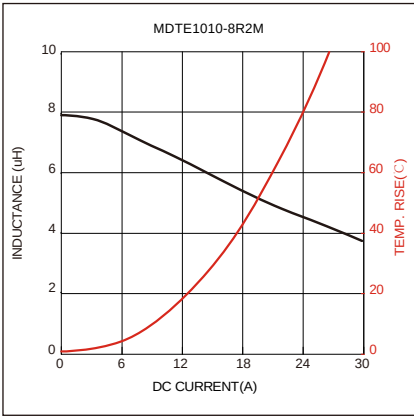
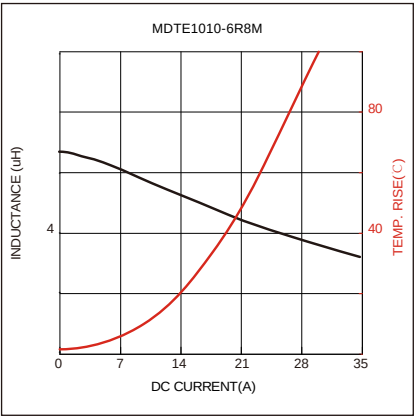
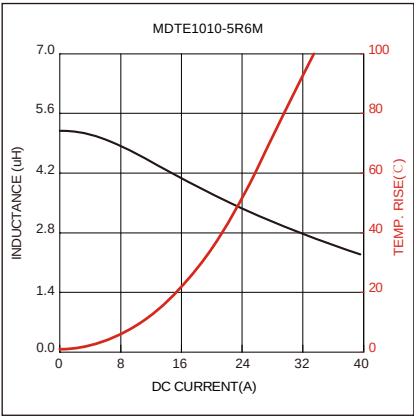
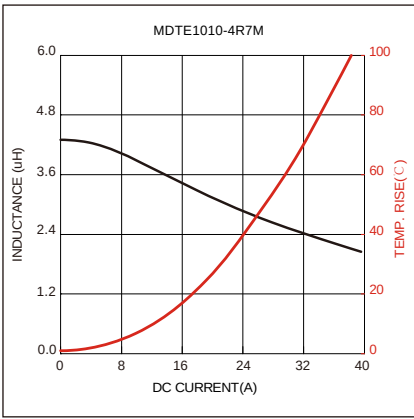
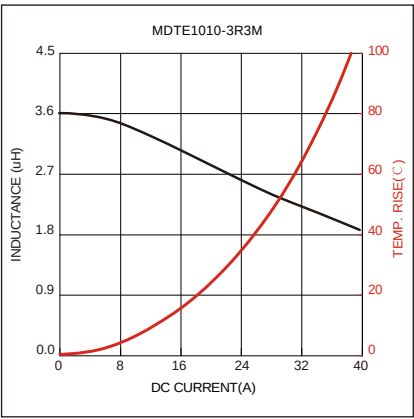


Electrical Properties:

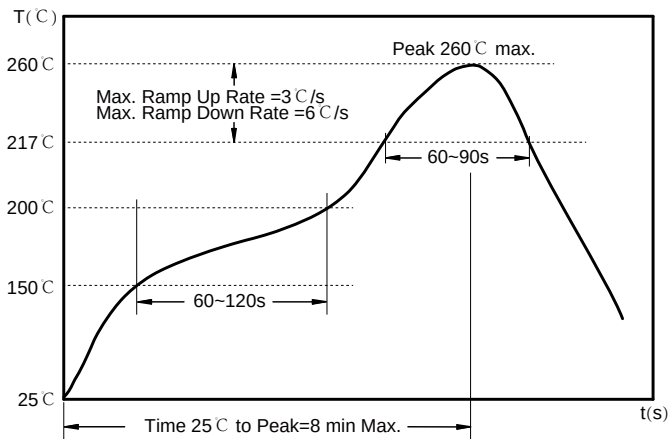
MDTE1010-2R2M	2.20	±20%	34.0	29.0	32.0	2.8	9.3±0.5
MDTE1010-3R3M	3.30	±20%	27.4	23.4	25.0	4.1	9.3±0.5
MDTE1010-4R7M	4.70	±20%	25.4	21.4	24.0	5.7	9.3±0.5
MDTE1010-5R6M	5.60	±20%	23.6	19.6	21.2	7.2	9.3±0.5
MDTE1010-6R8M	6.80	±20%	21.8	18.5	18.5	8.9	9.0±0.5
MDTE1010-8R2M	8.20	±20%	18.3	16.3	17.1	12.4	9.0±0.5
MDTE1010-100M	10.0	±20%	17.5	14.6	15.5	13.75	9.0±0.5
MDTE1010-150M	15.0	±20%	15.5	12.5	13.8	19.30	9.0±0.5

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T=40^{\circ}\text{C}$



Soldering Reflow:



Preheat condition: 150 ~ 200 °C / 60~120 sec.

Allowed time above 217 °C: 60~90 sec.

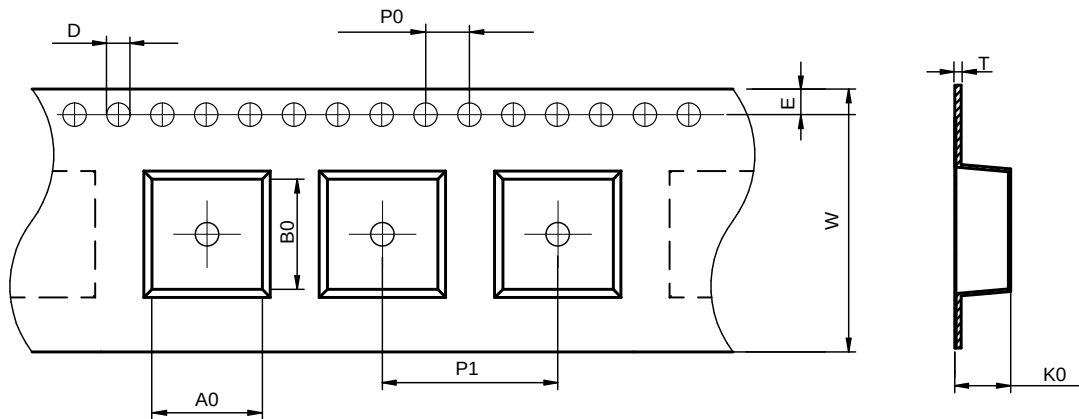
Max temperature: 260 °C.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

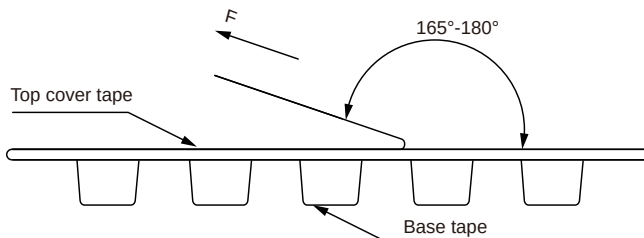
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE1010	12.4±0.1	11.5±0.1	1.5±0.1	4.0±0.1	16.0±0.1	24.0±0.3	10.3±0.1	1.75±0.1	0.5±0.05

Peel force of top cover tape:

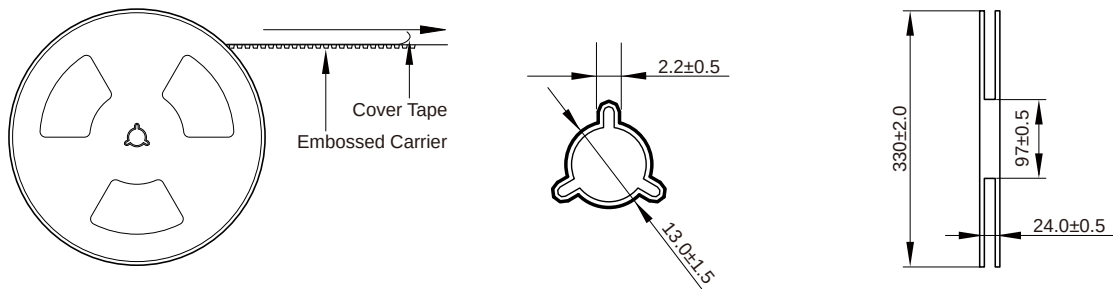


The peel force of top cover tape shall be between 0.1 to 1.3 N

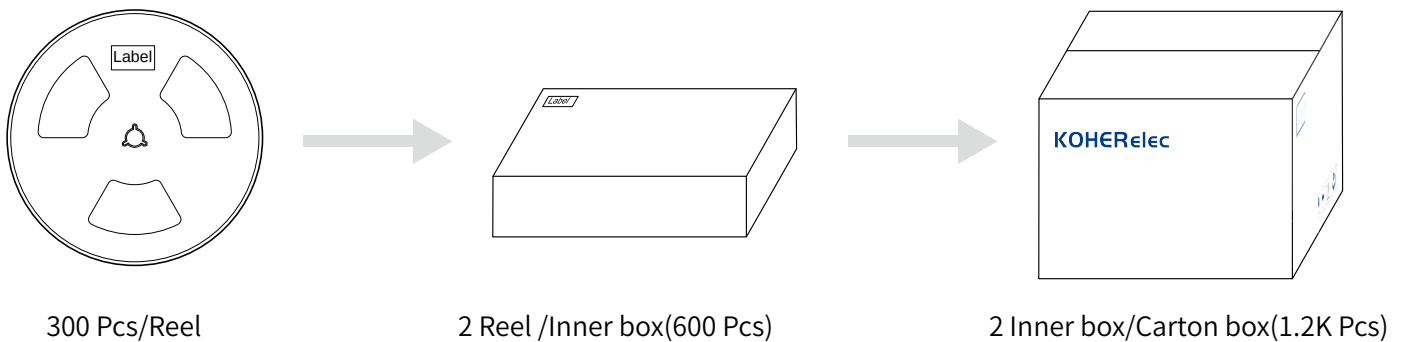
Product Marking:

Marking	Printing (Inductance)
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Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does. As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.